
[Upgrade to Revision]

R20TS1017EJ0100

Rev.1.00

RX23W Group

May. 20, 2024

BLE Module Firmware Integration Technology Rev.2.60

Outline

RX23W Group BLE Module Firmware Integration Technology has been updated from Rev.2.50 to 2.60.

Please update the product if you might be using it under any of the conditions described in section “2.1 Issue Fixed” below.

1. Products to Be Updated

RX23W Group BLE Module Firmware Integration Technology

Rev.1.00, 1.01, 1.10, 2.00, 2.10, 2.11, 2.20, 2.30, 2.31, 2.40, 2.50

2. Description

The main change is as follows. Refer to the Application Note’s Revision History for other changes.

[RX23W Group BLE Module Firmware Integration Technology Application Note](#)

2.1 Issue Fixed

The following issue has been fixed.

When the following three conditions are met for Bluetooth LE communication and the timing of packet send/receive operations (2) and (3) conflict, the R_BLE_Execute() API will not return.

- (1) Enabled RPA ^(*) resolution and RPA generation feature using R_BLE_GAP_EnableRpa() API.
- (2) Performing advertising, scanning, or initiating (connection request) operations.
- (3) Sending and receiving data over a connection with encryption enabled.

(*1) RPA : Resolvable Private Address

3. Updating the Product

Download the FIT module using the RX Smart Configurator and update the software component version.

For details, visit the following web site and refer to the RX Smart Configurator User's Guide.

[Firmware Integration Technology \(FIT\) | Renesas](#)

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	May.20.24	-	First edition issued

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